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CONSULTANT TRIP TO INDIA - FINAL REPORT

Program: Development of resins for reinforced composites. <u>Author:</u> Robert S. Irwin <u>Job Title:</u> Consultant — 15 March - 1 April (1985.) DP/IND/81/003/11-61/32.1.H

General Remarks

My actual itinerary is attached. I spent approximately three days at each of the following laboratories: I.I.T., Delhi; N.C.L., Pune; V.S.S.C., Trivandrum; I.P.C.L., Baroda. On the final day, before departure from India, I discussed my findings and recommendations with Drs. R. G. Kumble and Balakrishnan of the Department of Science and Technology, Government of India.

In this report I will discuss each visit separately and enumerate my findings and recommendations. Most of these were discussed with D.S.T. in Delhi, but I have included additional points which occurred to me in retrospect.

I. Indian Institute of Technology (I.I.T.). Delhi

The Principal Investigator for the resins program is Professor I. K. Varma, who heads a team of pre- and post-doctoral researchers - Ms. Sangita, Ms. Ranjana, Dr. H. S. Chaudhary, Dr. B. S. Rao, and Mr. A. K. Tomar. Key objective is identification of a preferred bismaleimide composition for broad general application and specification of synthesis and curing procedures as basis for semi-works scaled-up synthesis and evaluation at V.S.S.C. Related research is directed towards unsaturated polyester resins, for copolymerization with bismaleimides to relieve internal stresses created in high-temperature curing, and coupling agents for improved adhesion to glass.

° Lectures

I made the following presentations to the resin team and various other I.I.T. students and faculty.

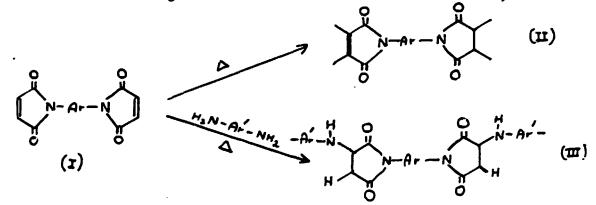
- "High temperature polymers" dealt with the principles involved in the selection of polymeric compositions for use at elevated temperatures, and examples of polyimides and other types finding current application.
- (2) "Polyimides for fiber reinforced composites" covered the use of polyimides not only as matrix resins but as potentially new reinforcing fibers. Bismaleimide

resins were compared and contrasted with various other types of imide-based resins in terms of economics, processibility, and properties.

- (3) "Organic reinforcing fibers" focussed primarily on Kevlar aramid, an aromatic polyamide, which complements the other common reinforcing fibers, glass and carbon, by providing increased toughness, non-catastrophic failure under compression, lower density, and intermediate economics.
- (4) "Structure-property relationships in mesophase polyest'r fibers" discussed the principles involved in the preparation of this new and still experimental class of high-performance reinforcing fibers.

'<u>Bismaleimide Technology - general</u>

Bismaleimides ($\bar{1}$) are synthesised by the combination of inexpensive maleic anhydride with a diamine (preferably aromatic). By heating (curing) up to 200°C or higher, a densely cross-linked structure (II) is produced by the addition polymerization of double-bonds; such structures are characteristically brittle. Alternatively, heating a bismaleimide in the presence of an aromatic diamine, $H_2N \cdot Ar' \cdot NH_2$, brings about so-called Michael addition of the amine groups to the double bonds to form more or less linear structures (III); compared with I, these have enhanced toughness but have diminished thermal stability.



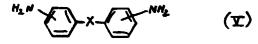
Usual practice is to cure the bismaleimide (I) in the presence of a limited proportion of the diamine, $H_2N \cdot Ar \cdot NH_2$, (Ar and Ar may be the same or different), chosen to provide an optimum balance of resin toughness and thermal stability. This may vary somewhat according to end-use. The basic advantages of bismaleimide resins are (a) processibility into reinforced composites similarly to the more common epoxy-resins, (b) ceiling use temperature range up to 250°C compared with <u>c</u>. 125°C for epoxies, (c) low cost.

At I.I.T. a variety of bismaleimide resins have been synthesised from the more commonly used aromatic diamines, and fairly comprehensively compared, e.g. in terms of rates, temperature ranges, and heat changes in curing; cross-linking efficiency; thermal stability; mechanical properties of composites. Individual composites have shown various advantages or disadvantages but, as yet, no clearly preferred candidate composite, for scaled-up evaluation, has emerged. To counteract the deterioration of mechanical properties, attributable to internal stresses set up under high-temperature curing conditions, copolymerization of the bismaleimides in curing with a small amount of a divinyl ester (IV) appears to be effective.

Comments and Recommendations

- (1) The absence of specific composite property goals lends a degree of indefiniteness to this program. I suggest that composites be prepared from some commercially available bismaleimide resins (preferably of known composition) to provide further experience in fabrication and perspective in terms of composite properties. According to <u>Handbook of Composites</u> (edited by G. Lubin, Van Nostrand Reinhold Co., New York and London, p. 109), bismaleimide prepreg materials are available from (a) Ferro Corporation, Ltd., Composites Division, Culver City, California, (b) Fiberite Corporation (advertisement attached), Winona, Minnesota, (c) Hexcel Corporation. Dublin, California, (d) U.S. Polymeric, Santa Ana, California. In addition Rhone-Poulenc produce Kerimiders. The attached properties for glass-fiber-reinforced thermoset polyimides and various epoxy resins ("1984-5 Modern Plastics Encyclopedia," P.O. Box 602, Hightstown, New Jersey 08520) may provide additional guidance.
- (2) Since the upper use temperature of bismaleimide resins is determined by the thermoxidative stability of the aliphatic maleimide adduct units, no significant improvement can be expected by the use of thermally more stable (and expensive) diamine units. On this basis 4,4'-oxydianiline, which is comparatively expensive because it is manufactured in limited quantities, is not to be preferred over the cheaper, more readily available 4,4'-methylenedianiline.

(3) The mechanical properties of bismaleimide composites are influenced mainly by the density of the cross-linking in curing, so that the actual structure of the diamines (V), either comprising the bismaleimide or added prior to curing, of the bisaniline type (which are of most interest) is less important.



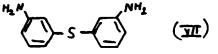
The main differences will be that flexible units (<u>m</u>-phenylene rings; 0 or S bridges) will provide somewhat lower flex modulus, but this may be of little consequence for most common applications. For this reason, 3,3'diaminodiphenyl sulfone (VI), which is available at a very low cost in India, in principle, should provide adequate composite mechanical properties, and on this basis should be considered seriously as preferred candidate, compared with 4,4'-methylenedianiline, which is the least expensive aromatic diamine outside of India.

- (4) Several conditions to the use of the diaminosulfone (VI) for bismaleimide resins must be considered.
 - (a) VI is suitable as a constituent of the bisimide but is not suitable as diamine for Michael addition. Its weak basicity in the latter use necessitates very high curing temperatures (>>200°C) which are likely to be unavailable to the average prepregger. However, the use of a VI-based bisimide with methylenedianiline as Michael adduct is quite satisfactory because Michael addition of less than 200°C is possible.

Can addition of VI be cat_iyzed to permit lower curing temperatures? Temperatures above 200°C seem to be essential for the addition reaction of the unsaturated maleimide groups with each other; can this be reduced by catalysis?

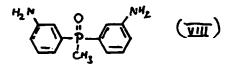
- (b) Is there a second supplier of VI, other than Hindustan Organic Chemicals? If not, users of a bismaleimide resin based on VI would be in a vulnerable position? As standard practice, the DuPont Company looks for two or more suppliers of each essential intermediate.
- (c) It is worth determining whether the manufacturers of VI can, by a

modest change in process conditions or at modest additional cost, produce the corresponding sulfide (VII).



VII would not require high curing temperatures. VII m¹; ht also be formed by reduction of VI, possibly at attractive cost.

(5) The phosphorus-containing resins such as that based on the diamine VIII have a quite outstanding level of flame resistance (L.O.I.=100) and a somewhat superior flex modulus.



However, the other non-phosphorus-containing resins also have very good flame resistance (L.O.I.>80); and therefore, the gains in properties with VIII, <u>et al.</u>, would not compensate for the undoubtedly higher cost and non-commercial availability of diamine VIII.

- (6) While appreciative of the reasons for incorporating a small amount of copolymerized divinyl ester in the resin to alleviate the suspected internal stresses engendered by a high cure temperature, I would point out that the presence of this material may diminish the upper use temperature by splitting out of H₂O and by absorption of moisture, and may introduce further complications in application of this technology. Internal strains usually result from differential thermal expansion and contraction of reinforcing fibers, compared with the matrix resin, and will be intensified by high curing temperatures. I recommend taking all steps possible to minimize the curing temperature with 100% bismaleimide resins.
- (7) While adhesion-to-glass was not discussed with me, I judge, from the research effort on coupling agents, that it is not entirely satisfactory. This is a rather major undertaking, and I question whether the problems may not lie in a mismatch of thermal expansions (discussed above) which could be alleviated by lowered curing temperatures. I also recommend a close look at whether the fibers are properly wetted by the resin prior to and during curing, which would be associated with the melting temperature

of the neat and partially cured resin, relative to the curing temperature after removal of solvent. Plasticizers (i.e., non-volatile solvents) for the resin may be key to lowered melting point and improved wetting.

From the research point-of-view it might be worthwhile to investigate an asymmetrical diamine for lowered melting point. 3,4'-Oxydianiline (IX), available as a development chemical from Mobay Chemical Corporation, may be a good candidate because it is the basis for Teijin's HM-50 high modulus aramid fiber and if this develops, the diamine could be inexpensive.



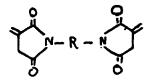
I might also suggest an evaluation of the diamine (X), which is available from National Starch Corporation, might lead to superior processibility (and properties); melting points should be reduced by virtue of its high flexibility. The all-para analog of X, which would be stiffer, may also be obtained from Mobay.

- (8) Since the resins program will be concluded in the next year or so, i.e. time is short, even though a clear technical case for preferring a particular bismaleimide candidate for scale-up is not in hand, I believe that economics plus information in hand at I.I.T., along with the experience at V.S.S.C. on the analogous bisitaconimide, provide a sound justification for scale-up, as of now, of the bismaleimide from 3,3'-diaminodiphenylsulfone (VI) as discussed earlier. If manpower and funding are available, I would favor the scale-up of the resin from 4,4'-methylenedianiline as well as the prospect for success here is very high. In both cases the latter diamine would be used as Michael adduct.
- (9) The attached notice of a short course on "High Temperature Polymers" may be of interest to resin program investigators because bismaleimides is one of the topics specifically covered.

II. Vikram Sarabhai Space Center (V.S.S.C.), Trivandrum

Dr. K. V. C. Rao, as Principal Investigator for the resins program, directs the work of a young and relatively inexperienced group - D. Chandra, R. George, and M. 7 Rao. Also associated with the program are S. K. Nema and Dr. R. Ramaswamy. A different group, headed by K. S. Sastri is equipped to perform scale-up resin syntheses and evaluations as required, for V.S.S.C. and other laboratories participating in the resins research; Dr. Shanmugam is a key member of this group.

The key research objective at V.S.S.C. is to determine whether bisitaconimides present a viable alternative to bismaleimide resins, in terms of processibility and composite properties. Itaconic acid can be obtained from plant sources in India and I assume that economic studies have established it as an attractive alternative to maleic acid. Currently, the V.S.S.C. program is focussed on the bisitaconimides from 4,4'-methylenedianiline (coded PIM-750) and 3,3'diaminodiphenylsulfone (BIS-400).



R = - (PIM - 750) $R = - (S0_2 - (BIS - 600))$

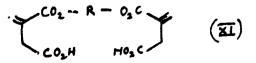
° Comments and Recommendations

- (1) Discussion of maleimide work at I.I.T. (above) is applicable also to bisita.onimides.
- (2) The key elements of this program seem to me to be rather self-evident.
 - (a) Side-by-side comparison of PIM-750 and BIS-400, in all aspects of process and composite properties with their better-known, bismaleimide analogs, using optimal conditions established for the latter (I.I.T. work and bismaleimide literature).
 - (b) Optimization of bisitaconimide process technology and composite properties, and a further comparison with bismaleimides under optimal conditions for each separately. Optimal may be best defined as providing, without processing problems, the best possible combination of composite properties, suitable for the same broad-based application. The property flexibility possible with each type of resin should also be compared.

- (c) Decision as to whether bisitaconimides are viable resin compositions in terms of processibility and composite properties and to proceed with a scaled-up evaluation, again making a comparison with bismaleimides, similarly scaled-up under optimum conditions.
- (2) I was not informed as to whether detailed comparisons of bisitaconimides and bismaleimides (as above) have been made, or whether the bisitaconimide resins have been optimized. I assume the latter to be the case because the technical problems posed to me did not bear directly on this situation but on relatively peripheral matters. I was not made aware of any basic problem to delay scaled-up evaluations of PIM-750 and/or BIS-400. Current experimentation did not appear to be addressing any problem on this issue.

I was not informed as to whether a detailed evaluation of bisitaconimide process and properties, e.g. percentage cross-linking, curing rates and temperature ranges, thermal stabilities, etc., had been completed. Such knowledge is necessary for scale-up.

- (3) The bisitaconimide technology practised at V.S.S.C. seems to differ in some respects from the bismaleimide technology at I.I.T., suggesting a possible need for closer coordination. Thus, for example, the former are imidized by heating in DMF whereas the latter are imidized by acetic anhydride AcONa. Again, with the former, diamine adducts are created with 10-20% diamine whereas, with the latter, 30% diamine has been used. I am not aware of any special reasons for such differences.
- (4) I felt that much of the current research at V.S.S.C. was not addressing the key issues. E.g.,
 - (a) isolation and purification of intermediate amide-acids (XI) and concern with their stability in solution appears to me to be irrelevant.



1.1

Amine-anhydride reactions are known to be quantitative, with negligible by-products, so high purity is expected. The use of

amide-acid as a resin is not a realistic option because the basic advantage of the imidized material is ability to cross-link by an addition reaction and avoidance of formation of void-forming condensation products such as water.

- (b) Copolymerization or blending of itaconimides and maleimides, while of mild interest, is unlikely to lead to a commercial product on the basis of economics. Other means are available for varying product properties, notably proportion and nature of amine adduct.
- (c) Use of 4,4'-oxydianiline as Michael adducts for PIM-750 and BIS-400 seems impractical for economic reasons, stated earlier. Main interest should be 4,4'-methylenedianiline.

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- (d) Utilization of lower-boiling, rather than alkylamide solvents for prepregging seems to introduce complications (concerning formation of Michael adducts) which are best avoided at this stage. This could be researched later on but is not a reason to delay scaled-up evaluation.
- (5) There is some question in my mind as to whether prepolymerization of 10-20% 4,4'-diaminodiphenylsulfone with BIS-400 bisitaconimide resin in DMF is an effective reaction, in view of the I.I.T. finding that a weak base such as this diaminosulfone undergoes Michael addition at a rapid rate only at temperatures above 200°C (DMF boils at 156°C). If this is so, then adduct is formed only in actual curing of the resin. This point should be checked and consideration given as to whether 4,4'-methylenedianiline might be a superior choice of Michael adduct for BIS-400.
- (6) Some concern was expressed about shelf life (stability) of prepolymer solutions in DMF. If this is important, DMAc or NMP, which are often better solvents, should be tested. However, it would appear to be more attractive for a resin manufacturer either to ship his product as a dry solid (thus avoiding the extra bulk of a solution) or as fiber prepregs - in both cases, stability of solutions is not a concern. Small increases in inherent viscosity of prepolymer, in powder form, were noted on storage at temperatures of about 60°C but not at 25°C. Since material will presumably be stored at room temperature, this

should not be a problem, especially if this small reaction has no effect on composite properties. Otherwise, one might consider the use of a polymerization inhibitor such as hydroquinone and exclusion of oxygen (air).

- (7) It was observed that cured composites of BIS-400 after exposure to air at 250°C for several hours retained room temperature mechanical properties very well on testing at 250°C. The PIM-750 actually improved in properties. This is undoubtedly the result of oxidative cross-linking of the tertiary hydrogens created in the itaconimide groups after addition reactions have eliminated the double bonds. With PIM-750 there is an additional opportunity for cross-linking via the reactive-CH₂-bridge group; this is well-established with other kinds of polymer based on 4,4'-methylenedianiline.
- (8) Dr. Rao raised the question as to how one could prepare a melt-processible bisitaconimide resin, eliminating the need for a solvent. For a lead on chis I would direct attention to D. O. Hummel, et al., J. Appl. Poly. Sci., 18, 2015 (1974) mixtures of bismaleimides of 4,4'-methylene-dianiline, 2,4-diaminotoluene, and 2,2,4-trimethylhexamethylenediamine melted in the range 75-125°C. Also, when 4,4'-methylenedianiline was replaced by "Jeffamine AP-22" in PMR-15, it was possible to eliminate

$$H_2 N + CH_2 \left(\begin{array}{c} + CH_2 \\ + CH_2 \end{array} \right) = 0, 1, 2$$

$$m = 0, 1, 2$$

need for a solvent, use hot melt prepregging procedures, and obtain good tack and drape: see T. L. St. Clair and R. A. Jewell, <u>National</u> <u>SAMPE Symposia Exhib.</u> 23, 520-7 (1978).

(9) <u>Scale-up</u>: Mr. Sastri described in detail their modus operandi for scaling-up a vinyl ester-styrene resin from I.I.T., a furfural resin from Sardar Patel University (Bombay), and a dimer acid polyamide resin (outside the UNDP project). My impression was that these were very competently handled in terms of promptness, generation of basic data for scale-up, and reaction to certain problems, such as gelation. (10) I was consulted by other V.S.S.C. personnel who are engaged in research on aramid reinforced fibers and who had a lot of questions related to DuPont's aramid fibers.

III. National Chemistry Laboratory (N.C.L.), Fune

In this large, well-equipped, and well-staffed laboratory, Dr. V. M. Nadkarni is Principal Investigator for the U.N.D.P. Resins Programme and supervises a young, enthusiastic research team consisting of Dr. Arun Shenoy, Dr. Jyoti Jog, and Miss Varsha, supported by D. R. Saine, and V. L. Shingarkali, technologists. Nadkarni directs concurrent work in related areas: (a) resins from liquid crystalline polymer melts, (b) cellulosic films, (c) bricks from sand and phenolic resins, (d) filled polyethylene, and (e) PET waste recovery. From consultations with various individuals, I would judge that Nadkarni leads a very capable group. I met also Dr. L. K. Doriaswamy, N.C.L. Director, Dr. R. A. Mashelkar, Head of the N.C.L. Chemical Engineering Division, and Dr. Bhide, Vice-Chancellor of the University of Pune, who is a technical coordinator of the U.N.D.P. resins program.

* <u>Lecture</u> on "Structure-Property Relationships in Mesophase Melt Polyester Fibers" was given to a large group of N.C.L. personnel.

° Comments

- (1) The resins program focusses on polymer alloys or blends of polyethylene terephthalate and polymethyl methacrylate, which have the common features of ester groups. The objective is to provide a range of compositions having properties intermediate between P E T and methacrylate, two readily available polymer systems. Hopefully, some new, unexpected, synergistic property combination may be uncovered. Additional variations will be introduced by the use of 1,4-cyclohexanedimethanol, an inexpensive reduction product of terephthalic acid in place of ethylene glycol. Since this diol can exist in both <u>cis</u> and <u>trans</u> forms, it is anticipated that property options may be further enhanced by controlling processing temperatures to give desired <u>cis:trans</u> ratios. I undertook to provide background on this isomerization process.
- (2) Polymer alloys of good mechanical properties and color have been demonstrated. Structural analysis has shown that the alloys produced by a single-screw extruder are well dispersed. The opacity of the alloy is undoubtedly the result of light-scattering from the fine particles of each phase; a

molecular blend is not formed. Still more intimate dispersion should be possible when their new, twin-screw extruder is in operation. An unusual feature of these alloys is an attractive surface pearlescence which remains to be exploited. A useful characteristic of the alloy technology is that alloying accelerates the rate of crystallization of the PET, suggesting that faster rates of molding may be possible.

(3) My impressions are that this work is progressing somewhat slowly but that otherwise it is on track. I was not informed of any unusual difficulties which are a road-block to the entire program. Dr. Nadkarni is well-informed in the field of polymer alloys. It remains to be seen whether his forthcoming, one-year's sabbatical leave at the University of Delaware will have a negative impact on the allow programs.

IV. Indian Petrochemical Corporation, Ltd. (I.P.C.L.), Baroda

The work on mica-filled polyethylene by Dr. J. Anand, Dr. Xavier, and Dr. Nesqvi, under Dr. Y. N. Sharma, Principal Investigator, was the most advanced of all the U.N.D.P. resins programs that I reviewed. I also met Dr. Patel, General Manager of Research, Dr. Venkatasuberamanian, Director of Research, and Dr. Ganwuly, I.P.C.L. Chairman, as well as a variety of other I.P.C.L. staff.

Lectures were presented on "Kevlar" aramid fibers" and "Mesophase melt polyesters."

° Comments and Recommendations.

(1) I.P.C.L. work is directed to the modification of a thermoplastic resin, polypropylene, which they manufacture, by incorporation of inorganic particulates (typically 30-50%) or chopped glass fiber. In early work they found that the combination of polypropylene with mica gave superior properties to alternative combinations involving high density polyethylene, CaCO₃, tale, or glass. The PP/mica combination has attractive economics (20¢ and 10¢/lb. respectively) and significantly increased modulus (stiffness), depending on mica content. The latter, however, had little effect on tensile, impact, or flexural strength. Various objects have been molded from PP/mica, including a briefcase. Chief negatives, perhaps not critical for many applications, are limited toughness and shrinkage on cooling from mold.

- (2) The scientific investigations carried out on this project appear to have been systematic and comprehensive. Studies have included type of blending, coupling at interfaces with silicones and titanates, particulate shape and size and grafting (at 2-4% level) of benzophenone ultraviolet stabilizers on to the PP, via radical sites created via mixing energy at 180°C.
- (3) Current efforts are directed at studying the aspect ratio of mica particles effect on properties. I may be able to provide some input as to rapid methods for assessing aspect ratios of mica particles other than laborious microscopic evaluation of individual particles. I also suggested that narrow particle size distributors could be separated by sedimentation methods and might give superior PP blends. One limitation on properties, in my opinion, is the interlaminar weakness of the mica particles themselves, and there seems to be no obvious way to take account of this. Otherwise, it might be possible to increase toughness by reducing the crystallinity of the PP. I would suggest applying the mechanical grafting technique to produce exten ive short grafts on the PP molecules which would modify crystallization. Ideally, one would design a linear copolymer of PP for reduced crystallinity, but this may be far beyond I.P.C.L.'s terms of reference. I will endeavor to find out whether or not PP copolymers are used for molding purposes in the U.S.A. D.S.T. would like to understand why American PP filled products can provide a strength of about 900 kg/cm 2 compared with the $300-400 \text{ kg/cm}^2$ attained by I.P.C.L.
- (4) In summary, it seems that it is left for R and D at I.P.C.L. to fine-tune the filled PP product. The major task now becomes that of identifying suitable end-uses.
- (5) Because of my acrylic fiber background and the fact that I.P.C.L. are expanding in acrylic fibers and actually will be using DuPont technology, I had significant discussions with the PAN fiber marketing and technical groups concerning various problems. It is possible that I.P.C.L. in the future might be interested in producing carbon fibers from PAN on a small scale.

sli/RSI

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1 :

"We started out using a glass to solve a test problem. And using it in 10 million cars."

Sometimes on the road to solving just one problem, the path takes a curious turn and a host of problems are solved.

That's what happened when Chrysler Corporation product engineers discovered that a glass filled phenolic disc brake piston used for its heat resistant properties during a brake dynamometer test turned out to have outstanding dimensional stability. And it weighed less than half of the steel part it replaced. Plus it offered outstanding manufacturing advantages, solved a material supply problem, and yielded significant cost savings. It's a sterling example of how quality improves

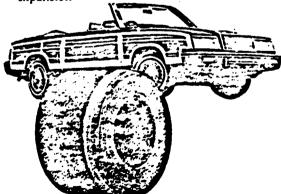
when engineering innovations and material characteristics come together.

Fiberite[®] engineered thermosets – phenolics, epoxies, polyimides, silicones, and melamines – are finding broad applicatio..s in the automotive and transportation industries with more yet to come.

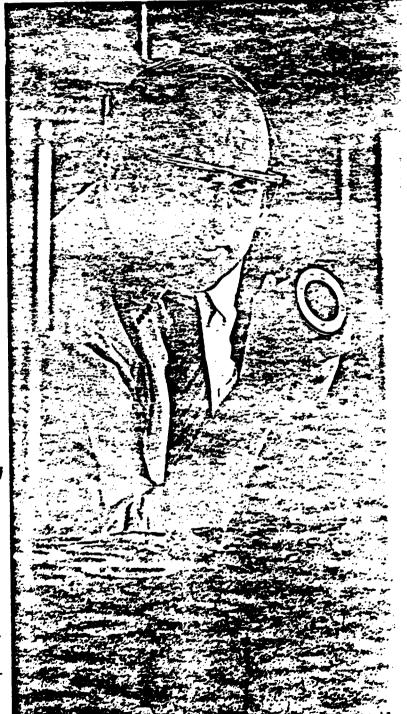
Fiberite® thermoset compounds offer outstanding engineering, manufacturing, and cost advantages not found in other materials.

• High heat resistance • Excellent adhesion to

- Dimensional stability inserts
- Creep resistance •
- High compressive
- Superior chemical and moisture resistance
 High impact strength
- strength • Low weight
- High impact strength
 Low pressure molding
- Low thermal expansion
- Low pressure molaing capability

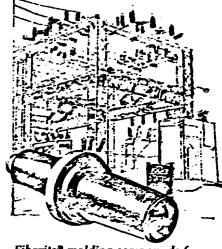


Many parts of Fiberite® compounds are already in mass production for transportation – brake systems, motor cases, drive train components, coils, timing gears, ignition systems, electronic components, EMI shielding, fuel injection systems, self-lubricated bearings.



assphenolic part ndwound up

Bob Campbell, Product Engineering/Quality Control Chemical Division, Chrysler Corporation

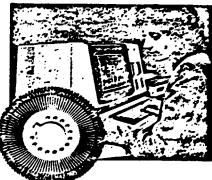


Fiberite[®] molding compounds for electric transmission offer excellent insulation characteristics under wet conditions, high dielectric strength, dimensional stability under stress and easy molding for difficult configurations.

 Low and high voltage transformer bushings

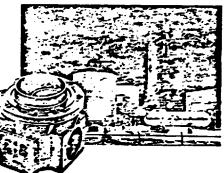
- Switchgear
- · Coils
- Electric motors
- Transformer housings
- Standoffs
- Insulators
- Underground transmission
- components
- Commutators

For the computer, business machine and telecommunications industry Fiberite® molding compounds offer parts of dimensional stability,



resistance to heat stress during vapor phase soldering and other assembly operations, excellent pin retention, and the capability to meet tight tolerances.

- Daisy print wheels
- Ink jet printing components
- Coil assemblies
- Opto couplers
- Diodes
- Fiber optics devices
- EMI shielding
- Semiconducting encapsulation
- Structural components
- Connectors
- Relay racks



In liquid and food handling systems, Fiberite® mold ...; compounds offer outstanding chemical resistance, heat resistance, and the ability to mold into complex shapes.

- Impellers
- Pump housings Sucker rods
- Sanitary liners
- Valve bodies
- Food handling devices
- Scrapper blades
 Dry bearings

In defense and ordnance applications, Fiberite[®] offers compounds that meet a wide range of MIL specs.

- Tactical rocket components
- Sabots
- Molded ablatives
- Small arms parts
- Gunstocks



Think of Fiberite when your design goes on the board. Or even before. Because the unique properties of Fiberite® engineered products can get ideas going. In addition to engineered thermoset molding compounds, Fiberite[®] is a qualified supplier of high-performance advanced composites, and preimpregnated filament roving. Call on Fiberite[®] for

- Materials selection
- Research and development
- Analysis and testing
- Fabrication information
- Process troubleshooting

For more information return this coupon, or call 507/454-3611.

Please send me more information on molded compounds performance and applications in the following areas. Transportation Computers/Business Machines/Telecommunications Defense Ordnance Liquid Handling Electric Transmission

Name		
Title		
Firm		<u> </u>
Address		
City	State	Zip
Telephone		

Mail to: Fiberite Corporation, 501 West 3rd Street, Winong, Minnesola 5598



ania in in

Circle 15 for reader service

• EMI shielding

High-Temperature Polymers-Synthesis, Properties and Applications June 19-21, 1985

High-temperature polymers are rapidly gaining worldwide importance for many uses in aerospace, electronics and high rechnology industries. This course presents an overview of the most recent advances in research and development of polymeric materials useful in the range of 200°C and above. Methods for preparing high-temperature linear thermoplastics, addition-type thermosets, and elastomers will be reviewed

Wednesday, June 19

Morning

- Historical Development of Thermally Stable Polymers
 Overview to include polyphenylenes, polyesters, poly-
- phenylenesulfides, polyamides, polyimidines, some polyheterocycles, and polybenzimidazoles P.E. Cassidy Aerospace Applications for High-Temperature
- Polymers Discussion of reinforced graphite/polyimide composites, linear and addition polyimide adhesives, films, and coatings. Related commercial spin-offs ... A.K. St. Clair
- Linear Thermoplastic Polyimides

Morning

Acetylene-Terminated Polymers

Synthetic routes for incorporating the acetylenic linkage into precursors and polymers; chemistry, physical, and mechanical properties of resulting polymers; use in electrical or electronic coatings, in advanced composites, or for applications calling for unusual chemical

 resistance
 A.B. Naselow
 Phosphazene Polymers: Synthesis, Properties, and Applications

- Evening

 Aromatic Heterocyclic Polymers Rigid rod and extended chain structures. Synthesis; liquid

with emphasis on the properties of these systems. Applications of thermally stable polymers as composite matrix resins, structural and film adhesives, molding powders, films, fibers, and coarings will be discussed. The course is designed for the practicing polymer chemist, engineer, or materials scientist who is currently working with or contemplating the use of high-temperature polymers.

Friday, June 21

Morning

- New and Unusual High-Temperature Polymers

and Terry L. St. Clair. Mrs. St. Clair is a Senior Research Scientist in the Materials Division at NASA Langley Research Center. She received a B.S. in chemistry from Queens College in 1969

and an M.S. in bioinorganic chemistry from Virginia Polytechnic Institute and State University in 1972. She is currently group leader for synthesis and development programs in the areas of metal-containing polymers and highperformance film technology.

Dr. St. Clair is Head of the Polymeric Materials Branch at NASA Langley Research Center. He received a B.S. in chemistry from Roanoke College in 1965 and a Ph.D. in organic chemistry from Virginia Polytechnic Institute and Scate University in 1972. He is responsible for R&D of hightemperature polymers for aerospace applications, including structural adhesives, advanced composites, films, and coatings.

Lecturers: Dr. Patrick E. Cassidy Prof. of Chem., Dept. of Chemistry Southwest Texas St. Univ., San Marcos, Tex.

Southwest Texas St. Univ., San Marcos, Tex. Dr. Andy C. Griffin

Prof. of Chemistry University of Southern Mississippi Hattiesburg, Mississippi

Dr. Frank W. Harris Prof. of Polymer Science and Chemistry Institute of Polymer Science University of Akron, Akron, Ohio

Dr. Art B. Naselow Manager, Materials Technology Department Hughes Aircraft Co., El Segundo, Calif.

Dr. Daniel A. Scola Senior Research Chemist United Technologies Research Center East Hartford, Connecticut

Dr. Robert E. Singler Research Chemisc, Polymer Research Div. Army Materials and Mechanics, Research Cnt. Watertown, Massachusetts

Dr. James F. Wolfe Program Manager, Ordered Polymers SRI International, Menlo Park, Calif.

REGISTRATION FEE: \$595.00 for the three day conference.

Crosslinked Polymers: Chemistry, Properties and Applications June 17-19, 1985

The objectives of this course is to acquaint scientists with the latest developments in various aspects of crosslinked polymers. The emphasis will be on the discussion of chemistry, processes, applications and fundamental principles unique to network polymers. Technologically most important classes of crosslinked polymers will be covered in greater detail. A comprehensive list of literature references for the past five years will be provided along with other lecture notes. The course is designed for the scientists and engineers who are already involved in the formulation or use of thermoserting systems (e.g. adhesives, composites, coatings, electronics, printing inks, etc.) and would like an update on the fundamental research and technology of these system.

Monday, June 17

Morning

Recent Developments in Crosslinking Reactions

Overview of crosslinking reactions, emphasis on new crosslinking techniques with extensive literature references for the period of 1978-1983

Evening

- Crosslinking of Acrylic Polymers Compositions of crosslinkable acrylic copolymers, functional groups, reaction rates, shelf stability, typical formulations and uses
- Characterization of Crosslinking Polymers Investigation of molecular architecture, swelling, mechanical measurement, gel permeation chromatography, chemorheology, and concept of effective crosslinks

Tuesday, June 18

Morning

 Morphology of Crosslinked Polymers and Interpenetrating Networks

Techniques for Measuring Kinetics of Crosslinking Reactions Experimental details of differential scanning calorimetry, infrared, gas chromatography. Interpretation of kinetics

data I.J. Goldfarb

Evening

 Chemistry of Radiation Induced Crosslinking Reactions

 Wednesday, June 19

Morning

- Crosslinked Polymers in Electronic Applications

Use of polymers in video disks, computer disks, photoresists, optical fibers and other high technology

areas M.J. Bowden

Scientific Program Chairman: Dr. S.S. Labana is Manager of the Polymer Science Department Research Staff, Ford Motor Company. He received his Ph.D. in 1963 from Cornell University, Ithaca, New York and did one vear postdoctoral research at the University of California, Berkeley. He has edited two books on crosslinked polymers and has recently completed a chapter on the subject for John Wiley Encyclopedia of Polymer Science and Engineering.

Lecturers: Dr. Ronald S. Bauer Shell Development Company Westhollow Research Center Houston, Texas

> Dr. Murrae J. Bowden Head, Chemistry and Polymer Research Department Central Service Organization of Regional Bell Operating Laboratories Murray Hill, New Jersey

Dr. I.J. Goldfarb Group Leader, Polymer Characterization Materials Laboratory Wright-Patterson Air Force Base, Ohio

- Dr. James F. Kinstle Polymer Research Polaroid Corporation Cambridge, Massachusetts
- Dr. Andrew Mercurio Department Manager of Polymer Resins and Monomers Pioneering Research Laboratory Rohm & Haas Company Spring House, Pennsylvania
- Dr. L.H. Sperling Professor of Chemical Engineering Lehigh University Bethlehem, Pennsylvania

REGISTRATION FEE: \$595.00 for the three day conference.

General Information

Enrollment:

The registration fee includes instruction, prepared notes (available only to those attending the courses), refreshments during coffee breaks, cocktails, mixer and banquet.

A registration form is attached. Enrollment may be made by individuals or companies. A reservation may be requested for industry, university, or government training employees who require time to obtain authorization. Advance registration is required. Check, purchase order, or government training contract should accompany the application. Check should be issued to:

Science and Technology Conferences.

1) Crosslinked Polymers: Chemistry, Properties and Applications conference - fee \$595.00.

2) High-Temperature Polymers: Synthesis, Properties and Applications conference - fee \$595.00.

The registration fee does not include room and meals. Each participant will be charged directly by the hotel or motel for room costs and extras.

Certificates will be awarded to participants attending the courses. Continuing Education units may be earned.

Accommodations:

Arrangements have been made with Mohorik Mountain House (914-255-100C), located a few miles from the campus to provide accommodations for the participants at reduced rates. Rates are \$90.00 per person, per day for single accommodation and \$80.00 per person, per day for double accommodation. Rates include all meals, with a great variety of courses available for your selection, and some recreational facilities. The rates do not include gratuities or tax. A \$50.00 deposit per person is required.

There is a limousine service between the New York Airports and Albany Airport and the village of New Paltz (hourly :chedule).

Complimentary transportation will be provided by the conference to Lake Mohonk from the New Paltz Bus Station and the Plaza Diner (drop-off place for the Hudson Valley Airporter and Limousine Service).

In addition to the Mohonk Mountain House, Super 8 Movel is available to our participants. Super 8 Motel is less than a year old unit, located in the town of New Paltz, seven miles from the lecture center at Mohonk Mountain House, but within walking distance for the shopping centers and restaurants. Special rates are available to our participants: Single/\$32.88 per day, Double (two persons)/\$36.88 per day, Twin (two persons)/\$38.88 per day. Prices include continental breakfast, but not sales tax. When you make reservations, (914-255-8865) indicate you are attending our conferences in order to receive the special rates. Participants should contact the preferred hotel directly. Rooms at Mohonk Mountain House will be held a limited time (a month before the course). After that time room reservations at Mohonk Mountain House will be accepted only if space is available, however rooms will be available at the motels. Please make arrangements early.

Schedule:

Lectures are scheduled in the mornings and in the evenings. The afternoons are free for recreation, reading, or participation in discussion groups, as the individual desires. Classes will be held at the Mohonk Mountain House. However, all college facilities will be available to the attendees. All conferences will end at 12:30 p.m. on the last day of the conference.

Exact information regarding final registration, check-in, living facilities, eating arrangements, and limousine transportation from New Paltz Bus Station or Plaza Diner to the Mohonk Mountain House will be provided upon receipt of the registration form.

A welcoming mixer on the first day of the conference enables participants and faculty to meet on an informal basis; group lunches and diners enable further interchange of ideas; and the concluding banquet provides the occasion for awarding certificates of completion of the course.

Recreational Facilities:

The Mohonk Mountain House, a 15-minute ride from the New Paltz campus, furnishes usual and unusual recreational activities, scenic grandeur and old-world charm. Ninety miles of hiking trails and bridle paths, clay tennis courts, one of the oldest golf courses in the area, swimming in the "Lake in the Sky" (as Mohonk Indians called it), a 305-room gingerbread-style mountain house, plus flower gardens, carriage rides, concerts, movies, art classes and lectures serve to provide you with beauty, relaxation and fun on Mohonk's 7,500 acres of fields, woods, lakes and streams.

The Sky Top Tower, at an altitude of 1,500 feet, can be seen for miles around and commands dramatic views of parts of six states. Hospitality continues to be the hallmark of Mohonk at the outset of its second century.

Further Inquiries:

Additional information may be obtained by writing or calling:

Dr. Angelos V. Patsis, Director Institute in Materials Science State University of New York Coykendall Science Building New Paltz, New York 12561 Telephone: (914) 257-2175

Although these are firm programs, contingencies may require a change without notice.

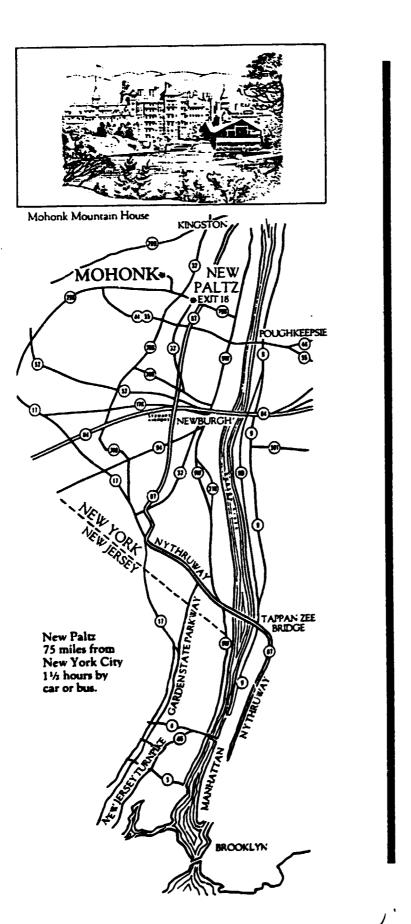
Registration Form

LAST NAME	FIRST	INITIAI.
COMPANY	······	Tel.:/
COMPANY ADDRESS		
SIGNATURE	TITLE	
CONFERENCE NAME	DATE FROM:	TO:
Please mail to: Institute In M	Science and Technology Conference	
Code 1 2	For further in	formation call: (914) 257-2

Accommodation Form

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NAME	Н	OME TELEPHO	ONE NUMBER
HOME ADDRESS		·	
CITY	STATE		ZIP CODE
BUSINESS ADDRESS (NAME	OF COMPANY)		
STREET AND NUMBER	CITY	STATE	ZIP CODE
SPECIAL INFORMATION AN	ND REQUESTS	NUMBE	ROFOUESTS
DATE AND TIME OF ARRIV	AL AT NEW PAL	Z DATE	OF DEPARTURE
Please include a \$50.00 d	leposit per pers	on.	
Please mail directly to: N	Mohonk Moun Lake Mohonk,		NY 12561
For further information	call: (914) 255-	1000	



Dr. Angelos V. Patsis, Director Institute In Materials Science Coykendall Science Building State University of New York New Paltz, New York 12561

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Postmaster: If Not Deliverable, Do Not Return

	Poly	yethylene a	nd ethylene o	copolymers	(Cant'd)		Polyimide		Poly- methyl- pentene	
	Γ	High density (Ce	int'd)	Cros	slinked	Thern	noplastic	Xastic		
	Copolymers (Cent'd)							-		
	Ethylene methyl- acrylate	Ultra high molecular weight	30% glass fiber- reinforced	Molding grade	Wire and cable grade	Unfilled	40% graphite- tilled	Thermoset, 50% glass fiber- reinforced	Unfilled	
	a	125-135	120-140					Thermoset	230-235	
						310-365	365			
2	E: 300-350	C: 400-500	I: 400-600	C: 240-450 I: 250-300	E: 250-300	C: 625-690	C: 690	C: 460 I: 390 T: 390	C: 510-550 I: 510-610 E: 510-650	
		5-20	10-20	<u> </u>	+	3-5	3-5	3-10	1-6	
1						3-4			2.0-3.5	
5.		0.040	0.002-0.006	0.007-0.090	0.020-0.050		1	0.002	0.012-0.030	
	1650	5600	9000	1600-4600	1500-3100	10.500-17.100	7600	6400	2100-2500	
T.	740	420-525	1.5	10-440	180-600	8-10	3	1	64-380	
	1650	3100-4000		1	1	12,500	1	1	2000-3300	
9.			7000	2000-5500		30,000-40,000	18,000	34.000		
0.			11,000	2000-6500		19,000-28,800	14,000	21.300		
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5 .		R50	R75			E52-99	E27	MT18	R35-85	
				Share D55-80	Shore D33-57					
6 .		130	48	100	100	45-56	38	13	65	
7.		110-120	250	105-145	100-173	530-680	680	660	120	
		155-180	265	130-225		ļ			175-195	
8.			11			2.3-2.6	41,4	8.5	4.0	
9.	0.942-0.945	0.94	1.28	0.95-1.45	0.91-1.40	1.36-1.43	1.65	1.6-1.7	0.833-0.835	
0	0.0	<0.01	0 02	0.01-0.06	0.01-0.06	0.24	0.14	0.7	0.01	
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1		710	500	230-550	620-760	560		450		
	Guif	Am Hoechst; Himont USA	Ferrer Schuimen Scee ed. p. 103); LNP; Thermofit Witson-FibertN	UBI (see ad, p. 60); Philips	Union Carbide; USI (see ad, p. 68)	Du Pont; Upjohr; Fluorocarbon; Monsento; Rhone-Poulenc	Du Pont; Fibertte (see ed. p. 28); Fixorocarbon; Rhone-Poulenc	Ciba-Giegy; Fiberite (see ed. p. 281; Upjehn; Rhone-Poulenc	Mitsun U S.A.	

MODERN PLASTICS ENCYCLOPEDIA 1984-1985 471

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•	C	ellulosic (c.	nf'd)	Chlori- nated PE	Ероху						
•	Cellulose ace- tate butyrate (Cent'd)				Bisphe	nol molding com	Novolak molding compoun				
٩	Molding compound	Cellulose acetate propionate molding compound	Celluiose nitrate	36-42% Ci extrusion grade	Glass fiber- reinforced	Mineral-filled	Low density glass sphere- filled	Mineral- and glass- filled, encapsulation	Mineral- and glass- filled, high temperature		
1.	140	190		125	Thermoset	Thermoset	Thermoset	Thermoset	Thermoset		
					1	1		145-155	195		
ĩ	C. 265-390 I: 335-480	C: 265-400 I: 335-515	C: 185-250	E: 300-400	C: 300-330 T: 280-380	C: 250-330 T: 250-380	C: 250-300 I: 250-300	C: 280-360 I: 290-350 T: 250-380	T: 340-400		
1	8-32	8-32	2-5	1	1-5	0.1-3	0.1-2	0.25-3.0	0.5-2.5		
	1.8-2.4	1.8-3.4	1		3.0-7.0	2.0-3.0	3.0-7.0		1.5-2.5		
5.	0.003-0.009	0.003-0.009	<u> </u>		0.001-0.008	0.002-0.010	0.006-0.010	0.004-0.008	0.004-0.007		
•	2600-6900	2000-7800	7000-8000	1500-1800	5000-20,000	4000-10,800	2500-4000	5000-12,500	6000-15,500		
7.	40-88	29-100	40-45	600-800	4	†		<u> </u>			
			1	1	1	1	[[†		
9.	2100-7500	2400-7000	2100-8000		18,000-40,000	18,000-40,000	10.000-15,000	24,000-48,000	30,000-48.000		
Q	1800-9300	2900-11,400	9000-11,000		8000-30,000	6000-18,000	5000-7000	10.000-21,800	10,000-21,800		
1.	50-200	60-215	190-220	ļ	3000		ļ	2100	2300-2400		
2.			<u> </u>	<u> </u>		650		L	660		
3	90-300	120-350			2000-4500	1400-2000	500-750	1400-2400	2300-2400		
4.	1.0-10.9	0.5-No break	5-7		0.3-10.0	0.3-0.5	0.15-0.25	0.3-0.5	0.4-0.45		
3.	R31-116	R10-122	R95-115	+	M100-112	M100-M112		M115	<u> </u>		
				Shore A65				Barcol 70-74	Barcol 78		
6	110-170	110-170	80-120		11-50	20-60	ł	18-43	35		
7.	113-202	111-228	140-160		225-500	225-500	200-250	310-446	500		
	130-227	147-250									
	4-8	4-8	5.5	1	4.0-10.0	4-35	4.0-6.0	8-31	17-24		
,	1.15-1.22	1.17-1.24	1.35-1.40		1.6-2.0	1.6-2.1	0.75-1.0	1.6-2.05	1.85-1.94		
0	0.9-2.2	1.2-2.8	1.0-2.0		0.04-0.20	0.03-0.20	0.2-1.0	0.04-0.29	0.17		
							·	0.15-0.3			
1	250-400	300-450	300-600		250-400	250-420	380-420	325-450	440-450		
	Essimen (see ed, p. 53)	Easiman (see ad. p. 53)	Chem, Development; George, P.D.	Dow Chem.	Fiberite (see ad, p. 28); Morton; Hyso; M & T	Fiberite (see ad, p. 28); Merton; Hysot; M & T; Plaskon	Fiberile (see ad, p. 28); Hysol	Fiberite (see ad. p. 28); Merten; Cosmic Plastics; Hyso; M & T; Plashon; U S. Protem	Cosmic Plastici Plaskon; U.S. Prolam		

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Resins and compounds (corra)

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						Epoxy (Contra)						
Materials	Properties			Novolak MC Casting resins and compounds								
2					ASTM test method	Glass- filled, high strength	Unfilled	Silica- filled	Aluminum- filled	Flexibilized	Cyclo- aliphatic	Polychia trifluoro- ethylene
	1. Melting temperature, *C. T _m (crystalline)				Thermoset	Thermoset	Thermoset	Thermcset	Thermoset	Thermoset	220	
Processing	2.	Processing temperature (C = compression; T = t I = injection; E = extrusi	range, transfer	•F.		C: 290-330 T: 290-330						C: 460-58 1: 500-600
Ü,	-	Molding pressure range,		<u>.</u>	 	2.5-5.0						15-60
Pro		Compression ratio				6-7						2.6
	5.	Mold (linear) shrinkage,	in./in.		0955	0.0002	0.001-0.010	0.0005-0.008	0.001-0.005	0.001-0.010		0.010-0.0
	6. Tensile strength at break, p.s.l.				D638 ⁸	18,000-27,000	4000-13,000	7000-13,000	7000-12,000	2000-10,000	8000-12,000	4500-600
	7.				0638 ^b		3-6	1-3	0.5-3	20-85	2-10	80-250
	8. 9.	Tensile yield strength, p. Compressive strength (r yield), p.s.i.		or	D638* D695	30,000-38,000	15,000-25.000	15.000-35.000	15.000-33,000	1000-14,000	15.000-20,000	5300 4600-740
	10. Flexural strength (rupture or yield), p.s.i.			id), p.s.i.	D790	50,000-70,000	13,000-21,000	8000-14,000	8500-24,000	1000-13,000	10.000-13.000	7400-11.
Mechanical	11.	Tensile modulus, 10 ³ p.s	rt.		D638 ^b		350			1-350	495	150-300
	12. Compressive modulus, 10 ³ p.s.i.		Ĺ.	D695							170-200	
ų.	13. Flexural modulus, 10 ³ p	.s.i.	73° F.	D790	2.8-4.2						190-260	
ž			_	200°F.	D790							
			_	250*F.	0790							
	300°F. 14. Izod impact, ftIb./in. of notch ('4-in, thick specmen)		300°F.	D790 D256A	25-34	0.2-1.0	0.3-0.45	0.4-1.6	2.3-5.0		2.5-5	
	15. Hardness	Hardness	Rock	well	D785		M80-110	M85-120	M55-85			R75-95
			Shore	e/Barcol	D2240/	Barcol 60-74				Shore D65-89		Shore D7
	16.	16. Coef. of linear thermal expansion, 10 ⁻⁶ in./in./*C.			02583 0696		45-65	20-40	5.5	20-100		36-70
ermai	17.	Deflection temperature under flexural load, "F.	2	264 p.s.i.	D648		115-550	160-550	190-600	73-250	200-450	
Ther			-	66 p.s.i,	D648							258
•	18.	Thermal conductivity, 10 seccm.2.°C.)" ⁴ cal	-cm./	C177		4.5	10-20	15-25			4.7-5.3
2	19.				0792	1.84	1.11-1.40	1.6-2.0	1.4-1.8	0.96-1.35	1 16-1.21	2 08-2 2
	20.	Water absorption (%-in, thick specimen), %		hr.	0570		0.08-0.15	0.04-0.1	0.1-4.0	0.27-0.5		0
Physical	21.	Dielectric strength (%-in thick specimen), short ti		nturation mil	0570 0149	380-400	300-500	300-550		235-400		500-600
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a — Boldface Relings identity advertisers in this issue. Where advertisements relate to the particular matenals described, reference to the page number is included. See the Directory of Supplement Classified Index, page 706, for additional suppliers of specialty materials and custom compounds.

456 MODERN PLASTICS ENCYCLOPEDIA 1984-1985

nget thermosetting plastics; D412 for elastomeric plastics; D882 for thin plastics sheeting.

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